

# Table of Contents

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<b>The Basics</b> .....	<b>1-1</b>
Objectives .....	1-1
Scientific / Engineering Notation .....	1-1
Voltage .....	1-2
Current .....	1-2
Resistance .....	1-2
Using Ohm's Law to Verify Device Specifications .....	1-3
Digital Numbers .....	1-5
Digital Logic .....	1-8
<b>Overview of Semiconductors and ATE</b> .....	<b>2-1</b>
Objectives .....	2-1
Wafers, Die, and Packages .....	2-1
ATE - Automated Test Equipment .....	2-5
Semiconductor Technologies .....	2-5
Digital and Analog Circuits .....	2-6
Types of ATE Systems .....	2-7
Tester Interface Boards .....	2-13
Wafer Probing .....	2-14
Probe Cards .....	2-16
Multi-site Probe Cards .....	2-17
Device Handlers .....	2-18
Temperature Forcing Units .....	2-20
<b>Introduction to Test</b> .....	<b>3-1</b>
Objectives .....	3-1
The Bottom Line .....	3-1
Basic Terms .....	3-1
What will be Tested? .....	3-6
Why Test? .....	3-9
Defects .....	3-10
What is The Correct Way to Test? .....	3-14
Quality, Reliability, and Environmental Testing. ....	3-17
Shake and Bake .....	3-20
Voltage Stress .....	3-21
Binning .....	3-23
Program Flow .....	3-24
Test Summary .....	3-25
Traceability .....	3-26
Introduction to Test Review. ....	3-27
<b>Test System Architecture</b> .....	<b>4-1</b>
Objectives .....	4-1
Basic Terms .....	4-1
The Test System .....	4-1

What's in a Test System? .....	4-3
DC Instrumentation .....	4-7
Functional/AC Instrumentation .....	4-17
Mechanical.....	4-40
Software .....	4-41
Basic Guidelines of Digital Semiconductor Test Engineering .....	4-44
Test System Architecture Review .....	4-45
<b>Device Specifications .....</b>	<b>5-1</b>
Objectives .....	5-1
Basic Terms .....	5-1
The Design Specification .....	5-1
The Test Specification .....	5-2
The Device Specification .....	5-2
Test Conditions and Limits .....	5-2
Parameters that Apply to DC Parametric Testing .....	5-2
Parameters that Apply to Functional and AC Testing .....	5-3
Logical Functions .....	5-3
Reading Device Specifications .....	5-3
256 x 4 RAM Specifications.....	5-5
Interpreting the Device Specification .....	5-8
Device Specifications and Test Conditions .....	5-9
<b>Shorts and Opens - PMU Method .....</b>	<b>6-1</b>
Objectives .....	6-1
Why Test for Shorts and Opens? .....	6-1
Shorts and Opens Serial Static Method .....	6-1
Shorts and Opens -Trouble Shooting .....	6-4
Power Bus Shorts Test .....	6-4
Shorts and Opens - Key Points .....	6-5
<b>Verifying DC Parameters .....</b>	<b>7-1</b>
Objectives .....	7-1
Basic Terms .....	7-1
The VPMU.....	7-2
DC Tests and the Hidden Resistance .....	7-3
VOH/IOH .....	7-4
VOL/IOL.....	7-8
IDD Gross Current.....	7-13
IDD Static Current .....	7-17
IDDQ Current .....	7-21
IDD Dynamic Current.....	7-25
Input Currents (IIL/IIH).....	7-29
Resistive Inputs Pullups and Pulldowns .....	7-36
Output Fanout .....	7-37
DC Fanout .....	7-37
AC Fanout .....	7-37
High Impedance Currents (IOZL/IOZH).....	7-39
Input Clamp (VI).....	7-44
Output Short Circuit Current (IOS).....	7-47

<b>Functional Testing</b> .....	<b>8-1</b>
Objectives: .....	8-1
Introduction to Functional Testing .....	8-1
Basic Terms .....	8-1
Functional Testing .....	8-2
Vector Data .....	8-13
Executing a Functional Test .....	8-14
Equation Based Timing .....	8-18
Functionally Testing a Device .....	8-19
Specification Test Conditions for the D Flip-Flop .....	8-23
Standard Functional Tests .....	8-29
Opens and Shorts - Functional Method .....	8-29
VIL/VIH .....	8-34
VOL/IOL VOH/IOH Functional Test .....	8-37
Resistive Output Loading .....	8-40
Input/Output Levels Relationship .....	8-41
Functional Z State / High Impedance Testing .....	8-42
Open Drain / Open Source Outputs .....	8-45
<b>Testing AC Parameters</b> .....	<b>9-1</b>
Objectives: .....	9-1
AC Parametric Testing .....	9-1
.....	9-13
AC Specifications from 256 x 4 Static RAM Data Sheet .....	9-14
Developing Functional Timing .....	9-15
<b>Device Characterization</b> .....	<b>10-1</b>
Objectives .....	10-1
Characterization Overview .....	10-1
Test Vectors and Characterization .....	10-2
Defining Characterization Parameters .....	10-2
Common Characterization Parameters .....	10-3
Use of Test System Tools .....	10-4
Binary Search - Output Timings .....	10-11
<b>Design For Testability</b> .....	<b>11-1</b>
Objectives .....	11-1
Design For Testability .....	11-1
Functional Testing and DFT .....	11-1
Fault Models .....	11-2
Automatic Test Pattern Generation .....	11-4
Fault Coverage .....	11-6
Types of Structured DFT .....	11-8
Boundary Scan IEEE 1149.1 .....	11-14
BIST .....	11-20
<b>Test Vector Development</b> .....	<b>12-1</b>
Objectives .....	12-1
Test Vectors .....	12-1
Example Vector File .....	12-1

Working with the Design Engineer .....	12-2
Creating Vectors by Hand .....	12-2
Tester Options (Memory Considerations) .....	12-3
Test Vector Examples .....	12-3
Simulation Data .....	12-7
Simulation for Test .....	12-9
<b>Test Program Development Issues .....</b>	<b>13-1</b>
Objectives: .....	13-1
What is the Primary Purpose of the Test Program? .....	13-1
Other Considerations .....	13-2
Initializing the Program .....	13-2
Verifying the Test Setup .....	13-2
Power On Sequencing .....	13-3
Power Off Sequencing .....	13-4
<b>Creating a Test Program .....</b>	<b>14-1</b>
Objectives: .....	14-1
Developing the Test Plan from the Device Specification .....	14-1
Designing the Test Hardware .....	14-2
Writing the Test Program .....	14-2
interface Board Tests .....	14-3
Tester Diagnostics .....	14-3
Running the Program the First Time .....	14-4
Verifying the Functional Test Setup .....	14-4
A Brief Discussion on Test Vectors .....	14-5
<b>Troubleshooting .....</b>	<b>15-1</b>
Objectives .....	15-1
Where to Begin .....	15-2
Example: IIL/IIH Test Failures .....	15-4
Debug Tools .....	15-5
<b>Qualifying and Documenting the Test Program .....</b>	<b>16-1</b>
Objectives .....	16-1
Qualification .....	16-1
Verify testing on handlers and probers .....	16-2
Documenting the Test Program .....	16-2
<b>CMOS Device Latchup .....</b>	<b>17-1</b>
Objectives: .....	17-1
What is Latch-up? .....	17-1
Latch-up Testing .....	17-3
Test Patterns .....	17-4
Test Procedure Summary .....	17-6
Applying Test Stimulus .....	17-6

**Glossary . . . . . Glossary-1**

**Answers to Review Questions . . . . .Answers-1**

Chapter 3 - Introduction to Test . . . . . Answers-1

Chapter 4 - Test System Architecture . . . . . Answers-4

Chapter 5 - Workbook Exercise . . . . . Answers-6

Chapter 5 - Device Specification . . . . . Answers-8

Chapter 6 - Opens and Shorts . . . . . Answers-9

Chapter 7 - DC Tests . . . . . Answers-10

Chapter 8 - Functional Test. . . . . Answers-12

Chapter 9 - AC Testing . . . . . Answers-15

Chapter 10 - Device Characterization . . . . . Answers-17

Chapter 11 - Design for Testability . . . . . Answers-18

Chapter 12 - Test Vector Development. . . . . Answers-21

Chapter 13 - Test Program Development issues . . . . . Answers-22

Chapter 14 - Creating a Test Program . . . . . Answers-24

Chapter 15 - Troubleshooting . . . . . Answers-25

Chapter 16 - Qualifying and Documenting the Test Program . . . . . Answers-27

**Index . . . . . Index-1**

